





**Thermal Characteristics**  $T_a=25$  Unless otherwise specified

PARAMETER		SYMBOL	UNIT	ES8G
Typical Thermal Resistance	Junction to ambient	$R_{J-A}$	/W	50 <sup>①</sup>
	Junction to lead	$R_{J-L}$		25 <sup>①</sup>
	Junction to case	$R_{J-C}$		15 <sup>①</sup>

Note(1)

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

**Ordering Information (Example)**

PREFERRED P/N	PACKAGE CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
ES8G	F1	Approximate 0.260	3000	/	42000	13" reel

**Characteristics(Typical)**

FIG.2: Forward Surge Current Capability

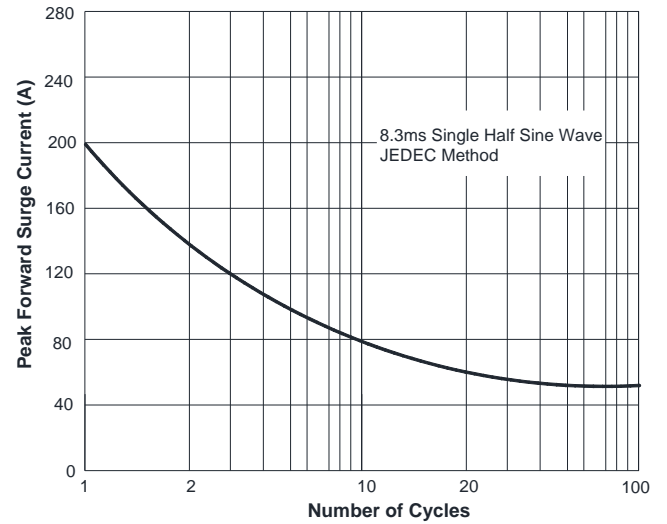


FIG.3: Typical Forward Voltage

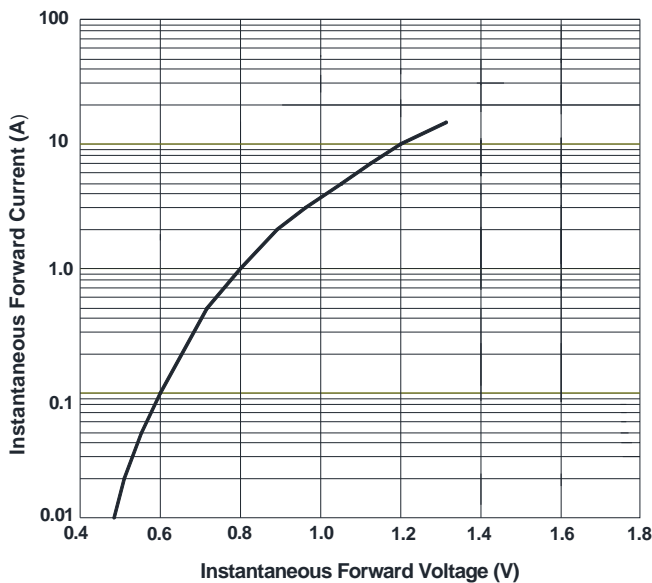
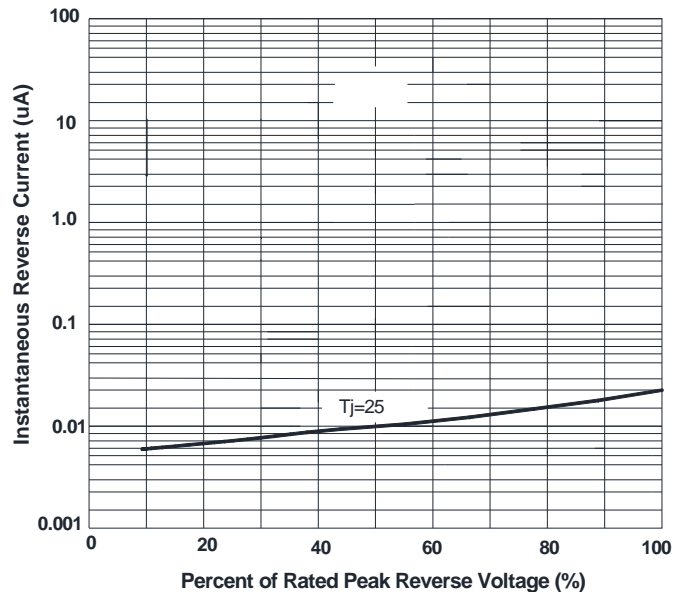


FIG.4: Typical Reverse Characteristics





**Outline Dimensions**

DO-214AB (SMC)		
Dim	Min	Max
A	6.60	7.11
B	2.85	3.27
C	5.59	6.22
D	7.75	8.13
E	1.99	2.61
F	0.15	0.31
G	0.76	1.52
H	0.05	0.20

**Suggested pad layout**



## Disclaimer

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